

## Bump Site Transfer for 6" Wafer Bumping

### Qualification Results Summary for Cu RDL Bump WLCSP at Chipbond

TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)	JEDEC <i>JESD22-A104</i>	3 x 77	Pass
Unbiased HAST (UHAST)	JEDEC <i>JESD22-A118</i>	3 x 77	Pass
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	3 x 77	Pass